

ABSTRACT OF THE DISCLOSURE

A socket device for receiving a connection pin is disclosed, the socket device including a substrate having an upper surface. The socket device includes a connection pad disposed on the upper surface and a first layer disposed on the upper surface and on the connection pad. The first
5 layer includes material having an overall positive coefficient of thermal expansion. The socket device includes a second layer disposed on the first layer. The second layer includes material having an overall negative coefficient of thermal expansion. The socket device also includes a contact hole formed in the first and second layers exposing a portion of the connection pad.